



11/23⁽⁼⁾
2021

G2C+ Investor Conference

This presentation contains some forward-looking statements that are subject to substantial risks and uncertainties. Typically, these statements contain words such as “anticipate” , “believe” , “could” , “estimate” , “expect” , “intend” , “plan” , “forecast” , “project” , “predict” , “potential” , “continue” , “may” , “should” , “will” , and “would” or similar words. You should consider these forward-looking statements carefully because such statements are only our expectations or projections about future events, and actual results may differ materially from those expressed or implied by such statements. The forward-looking statements in this presentation include, but are not limited to, growth rates for various markets estimated by third party sources, future products and technology development, widespread market acceptance of the hosted delivery model, future revenue growth and profitability. You should be cautioned that the forward-looking statements are no guarantee of our future performance. The forward-looking statements contained in this presentation are made only as of the date of this presentation and we undertake no obligation to update the forward-looking statements to reflect subsequent events or circumstances, except as required by law.

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Kent Chen , Co-head

Place: Hyatt

November 23th , 2021

- 2021 Q3 Operating Results
- Growth Opportunities &
Product Development

The image features the CSUN logo in a bold, italicized blue font in the upper left. The background is composed of several overlapping geometric shapes: a large red triangle pointing upwards, a smaller red triangle pointing downwards, and a dark blue triangle pointing upwards. The text '2021 Q3' and 'Operating Results' is positioned in the lower right, overlaid on the red and dark blue shapes.

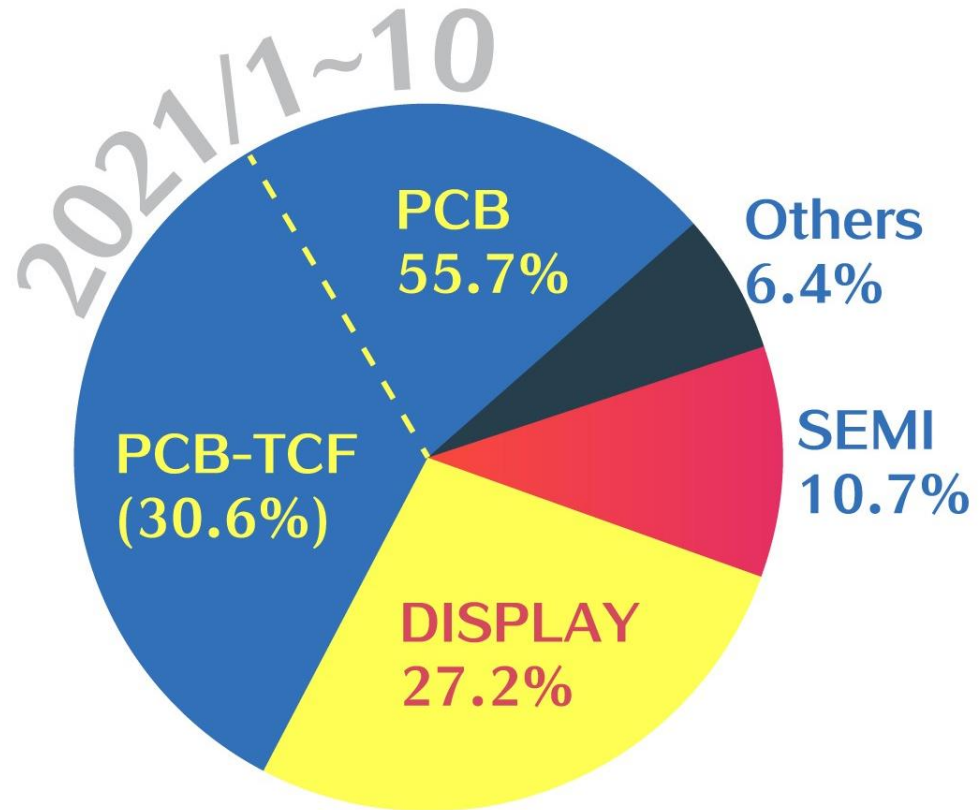
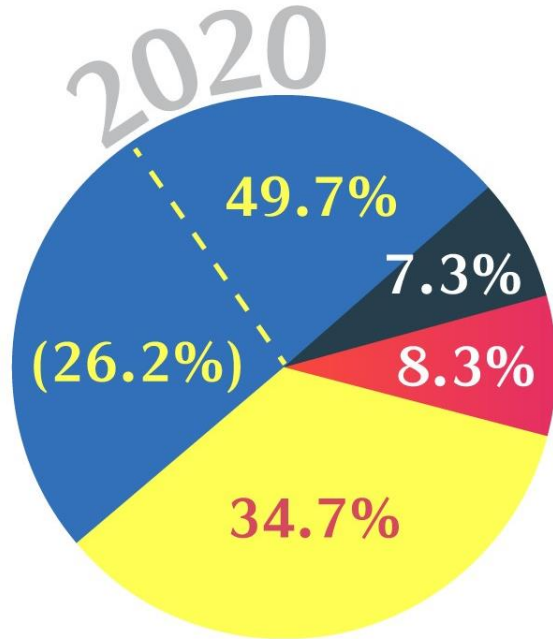
CSUN

2021 Q3

Operating Results

in TWD millions

	2021Q3 累計		2020Q3 累計		2020		2019		2018	
	Amount	%	Amount	%	Amount	%	Amount	%	Amount	%
Revenue-Consolidated	4,235	↑ 54.4%	2,742		4,086		4,438		5,700	
COGS	2,792	65.9%	1,641	59.9%	2,538	62.1%	3,170	71.4%	3,902	68.5%
Gross Margin	1,443	34.1%	1,100	40.1%	1,547	37.9%	1,268	28.6%	1,798	31.5%
Operating Expense	896	21.2%	757	27.6%	1,017	24.9%	954	21.5%	1,119	19.6%
Operating Income	547	12.9%	344	12.5%	531	13.0%	314	7.1%	679	11.9%
Net Non-Op. Profit	124	2.9%	56	2.1%	75	1.8%	104	2.3%	106	1.9%
Net Income before tax	671	15.8%	400	14.6%	606	14.8%	418	9.4%	785	13.8%
Net Income after tax	544	12.9%	319	11.6%	475	11.6%	338	7.6%	598	10.5%
Attribute to stockholder's of the parent	492	11.6%	299	10.9%	439	10.7%	312	7.0%	556	9.8%
ROE	17.94%		11.70%		16.46%		11.64%		21.83%	
EPS (NT\$/after tax)	\$3.24		\$1.97		\$2.94		\$2.09		\$3.73	
Debt Ratio	62.05%		59.99%		60.26%		58.66%		58.23%	





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Growth Opportunities
& Product Development



Computer
Terminal

Meta



元宇宙

High
Performance
Computing

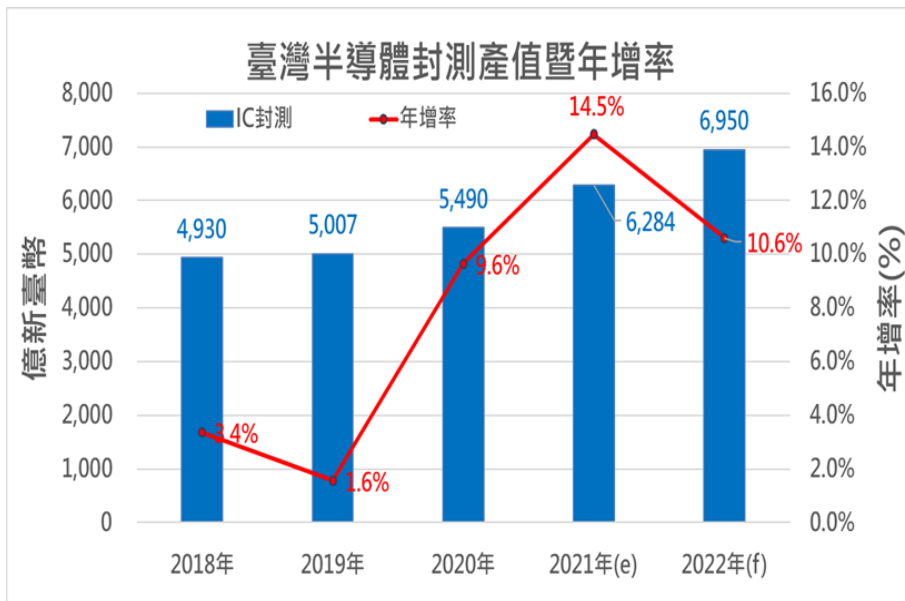
Low Latency
Transmission

Marketing Trending Topics/ Industry Development

- Metaverse & Low Earth Orbit shaping the future of virtual world
- Automated driving system expanding the use of electronics
- US-China tech war restructuring global supply chains

Stay tuned for ESG update

- 2021~2025 Automotive Semiconductor Growth potential: CAGR 12.5%(HPC、ADAS)
- High performance chip 212.4%(2021~2025)
- 2021-2026 Wearable Devices Growth Potential: CAGR 58% (Digitimes Research)



2021年第一季度全球前十封測大廠營收排名

排名	廠商	2020 Q1 營收	2021 Q1 營收	2021 Q1 市占率	2021 Q1 年增率
1	日月光	1,355	1,689	23.5%	24.6%
2	Amkor	1,153	1,326	18.5%	15.0%
3	江蘇長電	818	1,033	14.4%	26.3%
4	矽品	806	858	12.0%	6.4%
5	力成	624	646	9.0%	3.5%
6	通富微電	310	503	7.0%	62.0%
7	天水華天	242	400	5.6%	64.9%
8	京元電	232	267	3.7%	15.2%
9	順邦	185	227	3.2%	22.3%
10	南茂	177	225	3.1%	27.3%
前十大合計		5,903	7,174	100%	21.5%

註：(1)日月光：為日月光投控封裝與測試占比營收，並扣除矽品營收後數值；(2)市占率以前十大封測廠營收占比為主。

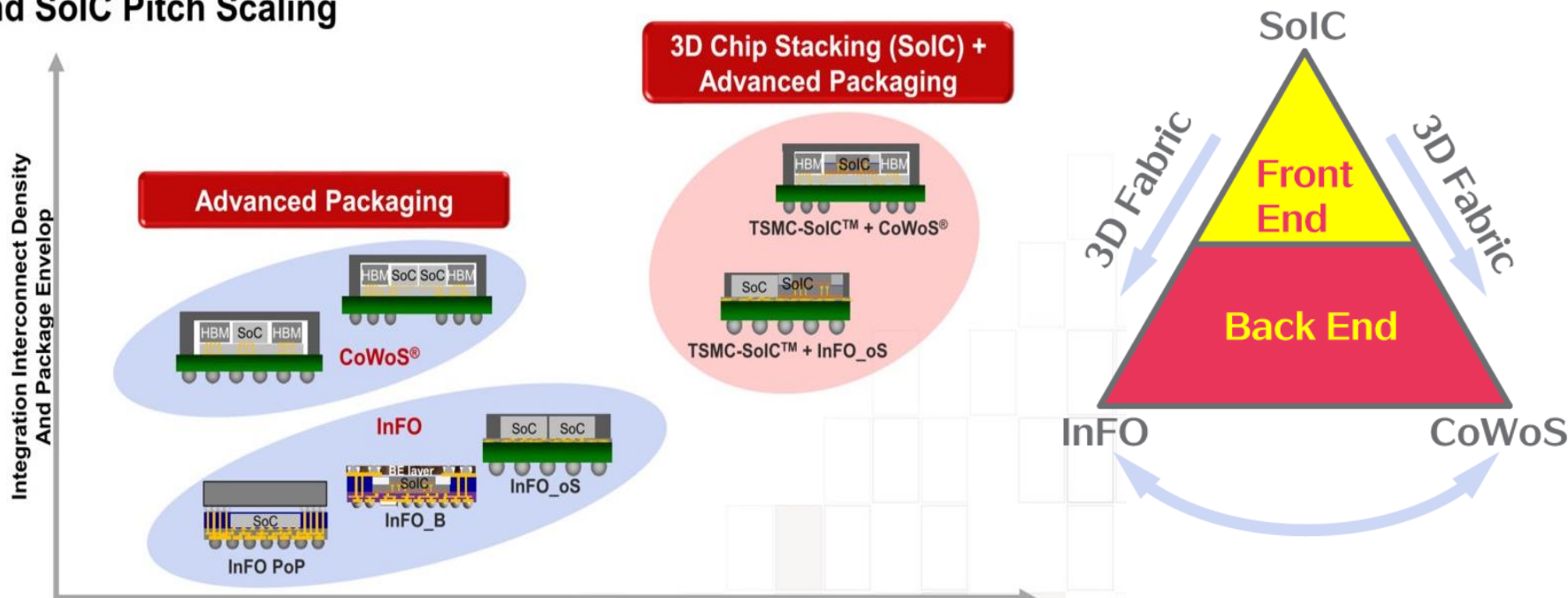
資料來源：TrendForce，2021年6月

單位：百萬美元

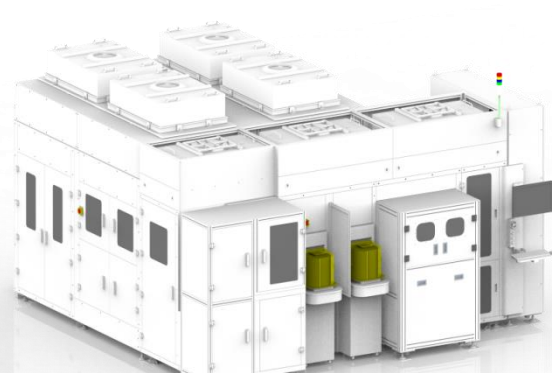
製表：科技組

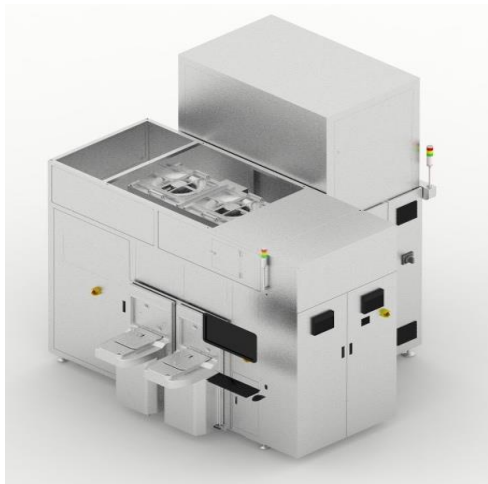
Chiplets are the next Advanced packaging process

- 3DFabrics updates- additional structures, Packaging Envelop Increase and SoIC Pitch Scaling



- As 3D integration advances towards mass production, the demand for equipment has increased.
- The production scale of 2.5D TSV has been growing steadily.
- Wafer-form Vacuum Laminator has entered SoW/SolS process and started manufacturing in a small volume.

**Auto oven****Carrier Bonder****Pre Anneal****Wafer Vacuum
Laminator**



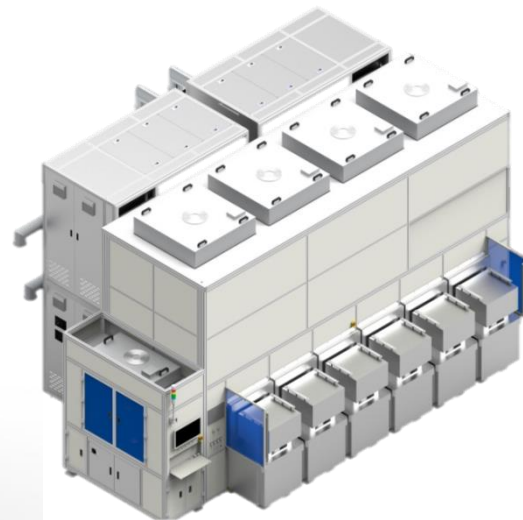
**vacuum high-
temperature oven**

PI curing equipment



Burn In Oven

Third generation semiconductor
Reliability test



PLP OVEN

automotive power
semiconductor



vacuum autoclave oven

Advanced Packaging de
void Process



**dust-free / oxygen-free /
high-temperature Oven**

Third generation semiconductor
baking Process

ABF process equipment demand continues to increase

ABF multi-cavity vacuum
lamination line



- Mini Led substrate demand continues to increase
- Ceramics substrate new product applications
- Unexpectedly Servo communication board



- With the smart display, a large number of mini LED are used as backlight applications
- Pushing up demand continues to rise substantially (Taiwan companies, Chinese mainland companies)



**Vacuum
lamination line**



Roller Laminator



**Exposure
System**



Mylar Peeler

The demand for automotive CMOS chip substrates and passive components has increased significantly.

And deploy low-earth-orbit satellite applications



Roller Laminator



Vacuum Laminator



Exposure System

In line with market trends, the substrate size has been advanced to 43 inches, and the application of larger substrate size has been jointly developed with customers.



43-inch automated
laminator

43-inch
PREHEATER

Oversized laminator

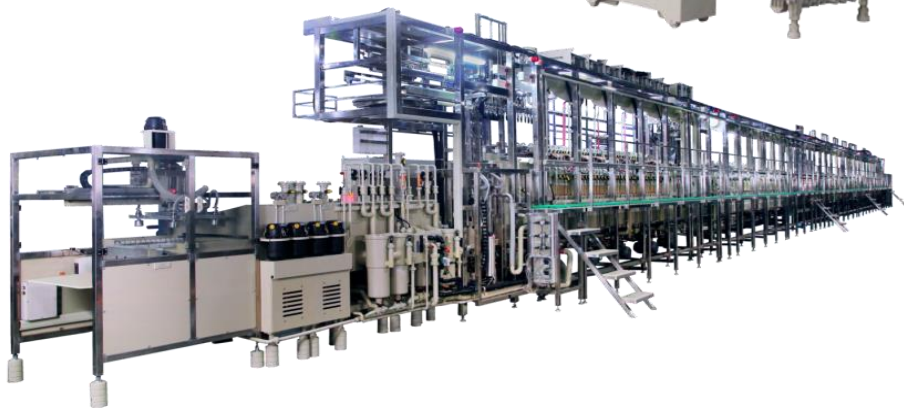
tcf 創峰
TOP CREATION





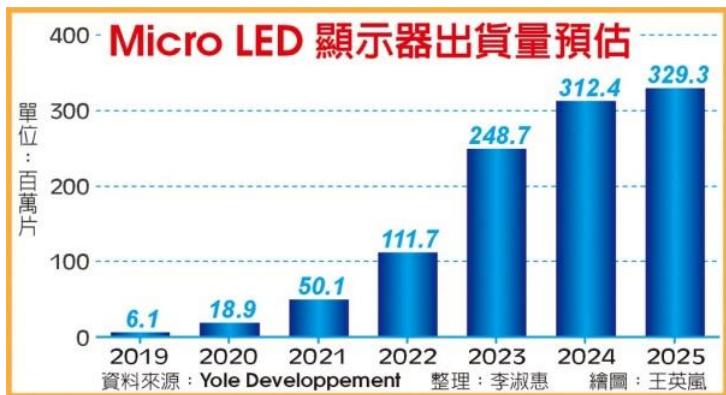
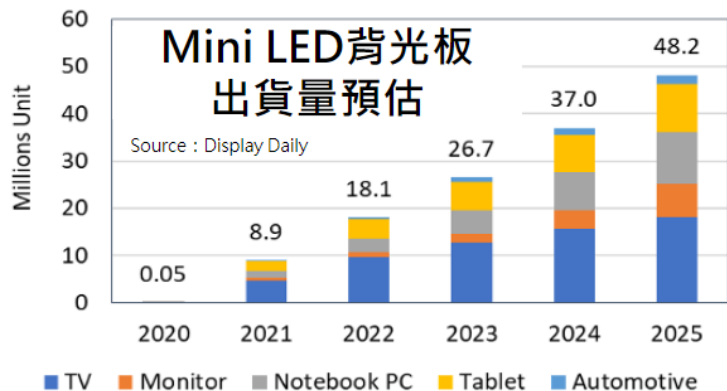
High Aspect Ratio Horizontal DSM & PTH

- Passed 40 : 1 engineering reliability qualification
- Advanced technologies lead 5G communication industrial



Vertical contact free DSM & PTH

- Meet ultra thin PCB needs, continuously order receiving
- Trend of package substrate application



Y2021 Marketing:

- In China, expansion of G8.6, G10.5 factory capacity and new plant. In Taiwan, capacity expansion and improvement of de-bottleneck.

Y2022 Opportunity and Challenge

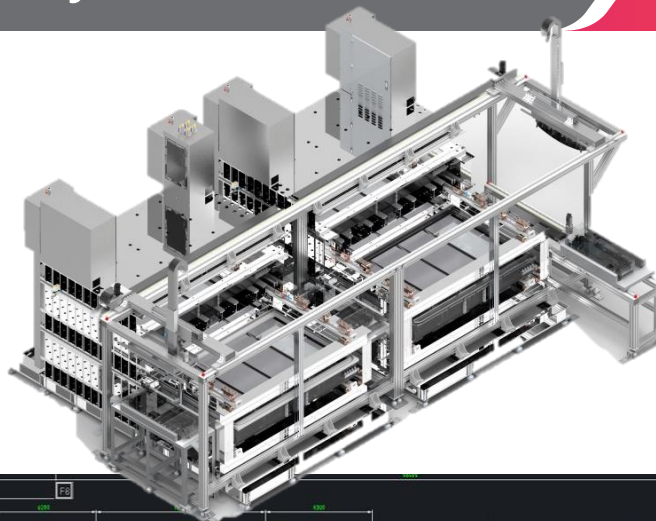
- The ascending trend of Automotive electronics brings Automotive panel manufacturing process automation line
- Products of Apple triggers wild application of Mini LED backlighting to FPD of Laptop PC, Tablet PC.
- Demands of manufacturing equipment for Micro LED display raised by investment of future product of AR/VR, wearable device and TV.
- Setting up G10.5 and G8.6 TFT/OLED plants in China gets to slow down, but capital expenditures of high-end panel production lines continues where it towards high value-added products.

~Go Premium

Dedicated production line for Automotive
Manufacturer + Production Automation

End Customer: Automotive manufacturers in the EU
and the US

- **Lamination Line:** de-voids → UV → Auto Unloading
- **Aging test Line:** Environmental Aging test Line for Automotive Display

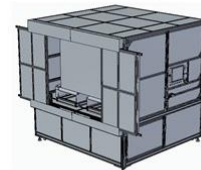
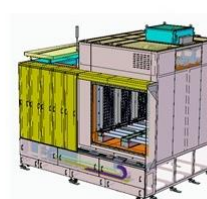
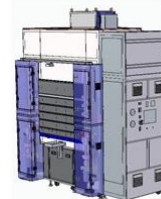
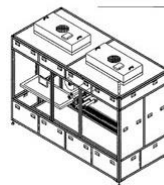


DCLN

Pre Cure

Post Cure

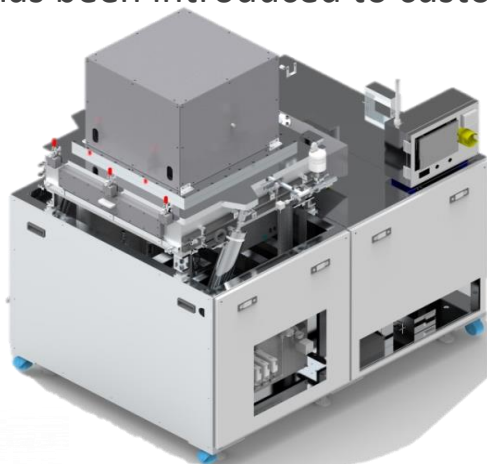
Cooler



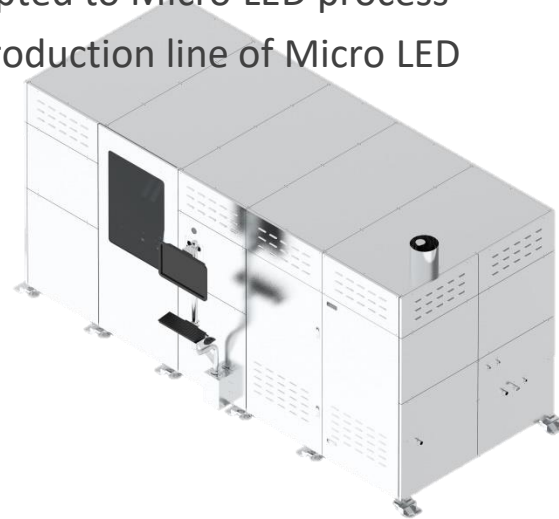
- Mini LED and the applications become one of the major high end panel display: Lamination Equipment
- Packaging equipment for Micro LED panel display put into process verification in customer's factory at 2022/Q1
- Plasma equipment certified by customer's process and being adopted to Micro LED process
- Auto pressure de-voids line has been introduced to customer's production line of Micro LED process



Lamination



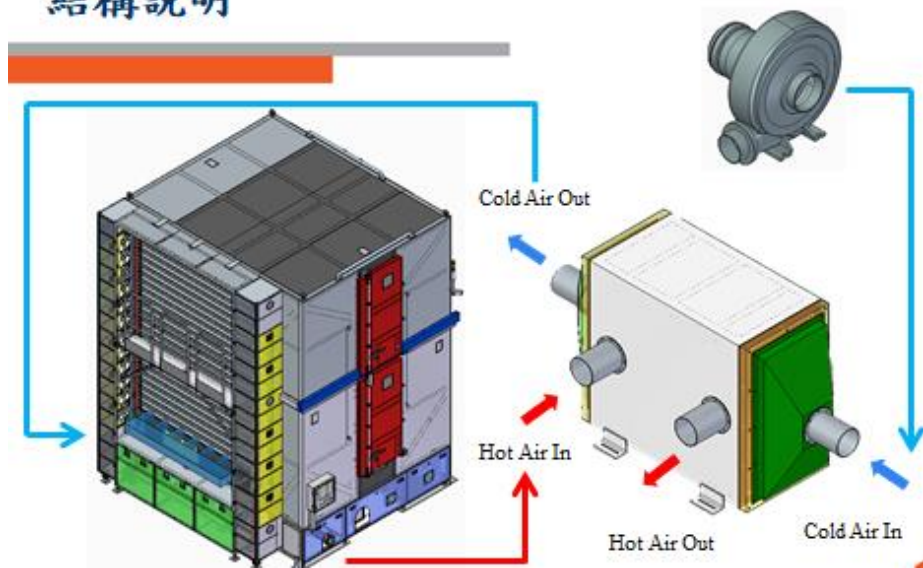
Plasma



Pressure De-voids

- Develop energy-saving system for large exhaust displacement OVEN that achieves heat exchange rate of 92.9%
- Each OVEN reduces carbon dioxide emissions by 26,326 kg CO₂e, which is equivalent to planting 2,500 trees. (12kg/tree)

結構說明



- **Prospect** to Meta Universe and Smart City
- Expansion of Advanced Packaging and application of IC Substrate in Taiwan and China
- Ascending demand of server/communication boards brings capital expenditures for production equipment
- Hot topic of Automotive panel display and self-driving vehicle / introduction of Micro LED direct display mass production
- **Creating customer value by integrated Core technology of 6 major partners via G2C cooperation platform**



G2C+

係由夥伴公司共組之團隊聯盟

Q & A



11/23(二)
2021

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Thank You
聯盟法人說明會